

Product and Process Change Notice

PCN No.	PCN03177	PCN Date	10/4/2024	Effective Date	9/20/2024
Title	OSE Material Change SOIC16 1 MB Package				

Type: Major Change

Die Thickness and Au Wire for the 1Mb SOIC16

Reason For Change

Long term improvement for device reliability.

Affected Products

Part Number	Description	Part Number	Description
MR10Q010SC	Commercial Temp.	MR10Q010SCR	Commercial Temp., T&R
MR10Q010CSC	Industrial Temp.	MR10Q010CSCR	Industrial Temp., T&R
MR10Q010VSC	Extended Temp	MR10Q010VSCR	Extended Temp., T&R

Impact on Form, Fit, Function, Quality or Reliability

No impact

Proposed First Ship Date for Change:

12/1/2024

Key Material Differences

Material	OSE From	OSE To
Wire	LT 0.8 Mil Au Wire (4N) / HP	LT 0.8 Mil AU Wire (2N) / HS-U
Die Thickness	6 Mil	4 Mil

Product Identifier

Assembly site code = O OSE

Supplier Qual Plan Schedule and Results

Qualification is complete and all Everspin requirements met; a qualification report is available on request.

Date Qualification Samples Are Available:


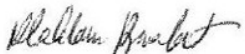


Samples are generally available now please request your specific part number to your Everspin Sales contact.

Acceptance of Change

Everspin will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice. QUA03178 QR Compliance documents requested.

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Contact Information		Sample Information <input checked="" type="checkbox"/> Samples Available Now
Everspin Quality Everspin Technologies (480) 347-1084 bonnie.paro@everspin.com		Contact Everspin sales: http://www.everspin.com/contact-us-everspin-technologies If using the on-line sample request, please refer to this PCN # to receive samples.
Originator		
<u>Date</u> 10/2/2024	<u>Title</u> SMTS Quality Engineer	<u>Name</u> Bonnie S. Hall-Paro  Electronic signature on file.
Approval and Release		
<u>Date</u> 10/3/2024	<u>Title</u> VP of Fab Ops & Quality	<u>Name</u> Khaldoun Barakat  Electronic signature on file.
<u>Date</u> 10/3/2024	<u>Title</u> VP of Backend Operations	<u>Name</u> Amit Shah  Electronic signature on file.
<u>Date</u> 10/3/2024	<u>Title</u> VP Sales & Business Development	<u>Name</u> David Schrenk 
<u>Date</u> 10/4/2024	<u>Title</u> Sr. Director of Marketing	<u>Name</u> Joe OHare 